

10-12-06

ITW



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re: Appn. Ser. No. 10/733,672 : Art Unit 2835

Filed 12/11/03 : M.V. Datskovsky

Inventors L.S. Mok et al. : Atty Dkt No. YOR920030186US1

For: CHIP PACKAGING MODULE WITH ACTIVE COOLING MECHANISMS

EXPRESS MAIL CERTIFICATE

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Va. 22313- 1450  
Sir:

Express Mail Label No.ED 882494103 US  
Date of Deposit 10/14/06

I hereby certify that the following attached paper or fee

Response to 9/18/06 Office Communication

It is hereby certified that this document is being deposited with the United States Postal Service  
"Express Class Mail" service addressed to

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Va. 22313- 1450

on 10/12/06

by

Alvin J. Riddles

Typed or printed name of person making deposit.

*Alvin J. Riddles 10/12/06*  
Signature and date of person making deposit.



Express Mail Label No. ED 882494103 US

Date of Deposit 10/12/06

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re: Appn. Ser. No. 10/733,672

Art Unit 2835

Filed 12/11/03

M.V. Datskovsky

Inventors L.S. Mok et al.

:Atty Dkt No. YOR920030186US1

For: CHIP PACKAGING MODULE WITH ACTIVE COOLING MECHANISMS

Response to 9/18/06 Office Communication

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Va. 22313- 1450  
Sir:

Receipt of the 9/18/06 Office Communication, containing an assertion of abandonment resulting from a reply to a 12/21/05 Office Communication, assumed as not being received, is acknowledged herewith. However, the assertion is refuted by the attached receipt stamp indicating that a response was received 1/20/06.

The response included the response, an Information Disclosure Transmittal with reference copies and proposed replacement informal drawings transmitted under the Express Mail Label No. ED 882445249US.

Respectfully submitted,

*Alvin J. Riddles* 10/12/06

Alvin J. Riddles

Reg. No. 17862



PLEASE STAMP AND RETURN

Appn. Ser No. 10/733,672 : Art Unit. 2835

Filed 12/11/03 : Exr. M.V. Detskovskiy

Inventor L.S. Mok et al : Atty Dkt. YDR920030186 US1

RECEIVED IN THE U.S. PATENT AND TRADEMARK OFFICE

RESPONSE TO 12/21/05 OFFICE COMMUNICATION



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re. Appn. Ser. No. 10/733,672

:

Art Unit 2835

Filed 12/11/03

:

Examiner M.V. Dotskoyskiy

Inventors L.S.Mok et al.

:

Atty. Dkt. No. YOR920030186US1

For: CHIP PACKAGING MODULE WITH ACTIVE COOLING MECHANISMS

EXPRESS MAIL CERTIFICATE

Commissioner for Patents  
P.O. Box 1450  
Alexandria Va. 22313-1450  
Sir:

Express Mail Label No. ED 882445249 US  
Date of Deposit 1/20/06

I hereby certify that the following attached paper or fee

Response to 12/21/05, Office Communication - Requirement for restriction,

Information Disclosure Transmittal with reference copies, and,

Replacement Informal Drawing Submission - 9 sheets

Are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, Va. 22313-1450.

Alvin J. Riddles

Typed or printed name of person mailing paper or fee

*Alvin J. Riddles 1/20/06*

Signature and date of person mailing paper or fee.